CYUSB2343-40LTXI

Package: PG-UQFN-40-4

All relevant reliability stress tests according to JEDEC JESD47 are assessed as PASS. The results detailed in this document may reference generic data

Table 1 Accelerated lifetime simulation tests for device qualification

Test description	Abbr.	Condition	Duration	Parts	Lots	Fails
High temperature operating life *JESD22-A108, JESD85*	HTOL	125°C, $V_{cc,max}$	1000 h	77	3	0
Early life failure rate *JESD22-A108, JESD74*	ELFR	125°C, $V_{cc,max}$	96 h	800	3	0
Low temperature operating life *JESD22-A108*	LTOL	covered by wafer technology qualifcation		n.a.	n.a.	0

Table 2 Electrical verification tests

Test description	Abbr.	Condition / comment	Parts	Lots	Result
Electrical parameter assessment	ED	Test at room, hot, cold temperature	10	3	Pass
ESD human body model *JS-001*	ESD HBM	Class 2 (2000 V to < 4000 V), all pins: 2 kV	15	1	Pass
ESD charged device model[1] *JS-002*	ESD CDM	Class C2a (500 V to < 750 V), all pins: 500 V	3	1	Pass
Latch-up *JESD78*	LU	Class II.A	3	1	Pass

Table 3 Accelerated environment stress tests for package qualification

Test description	Abbr.	Condition	Duration	Parts	Lots	Fails
High temperature storage life *JESD22-A103*	HTSL	150°C	1000 h	77	3	0
Preconditioning *JESD22-A113, J-STD-20*	PC	MSL 3, soak at 30°C/60% RH, 3× reflow at 260°C	192 h	before HAST, uHAST, TC		0
Highly accelerated temperature and humidity stress *JESD22-A110*	HAST	130°C, 85% RH	96 h	77	3	0
Unbiased highly accelerated temperature and humidity stress *JESD22-A118*	UHAST	130°C, 85% RH	96 h	77	3	0
Temperature cycling *JESD22-A104*	TC	-55°C to 125°C	1000 ×	77	3	0

Table 4 Package assembly integrity tests

Test description	Abbr.	Condition / comment	Parts	Lots	Result
Solder Ball Shear *JESD22-B117*	SBS	For Ball Grid Arrays (BGA) only	n.a.	n.a.	n.a.
Wire bond pull *JESD22-B120*	BPS	30 bonds from a minimum of 5 parts	5	1	Pass
Bond shear *JESD22-B116*	BS	30 bonds from a minimum of 5 parts	5	1	Pass

[1] voltage refers to test condition (TC) mentioned in the standard

Test description	Abbr.	Condition / comment	Parts	Lots	Result
Solderability *J-STD-002*	SD	Wetting and de-wetting	3	3	Pass
Tin whisker acceptance *JESD22-A121, requ. of JESD201*	WSR	Covered by package platform qualification	n.a.	n.a.	Pass
Physical dimensions *JESD22-B100*	PD	Covered by package platform qualification	10	1	Pass

Do you have a question about any aspect of this document?
Contact us: erratum@infineon.com

Trademarks
All referenced product or service names and trademarks are the property of their respective owners.

Edition 2026-10-27
Published by
Infineon Technologies AG
81726 Munich
Germany

© 2026 Infineon Technologies AG
and its affiliates. All rights reserved.

Public

Stay connected!

Scan QR code and explore offering
www.infineon.com

Important Notice

Products are sold or provided and delivered by Infineon Technologies AG and its affiliates ("Infineon") subject to the terms and conditions of the frame supply contract or other written agreement(s) executed by a customer and Infineon or, in the absence of the foregoing, the applicable Sales Conditions of Infineon.
General terms and conditions of a customer or deviations from applicable Sales Conditions of Infineon shall only be binding for Infineon if and to the extent Infineon has given its express written consent.

To the fullest extent permissible pursuant to applicable law, with respect to any information given in this document or in any associated documentation, Infineon disclaims all warranties and liabilities of any kind, whether express or implied, including but not limited to any warranties of merchantability, suitability of the products for the intended application or the specific use, or non-infringement of third-party rights.

Subject to the development and release of the products for series supply by Infineon, the technical specifications of the products are set forth in the relevant final datasheet provided by Infineon and, if any, agreed and signed specifications. Infineon's customers are required to evaluate the suitability of the products for the intended application or specific use.

The information given in this document is subject to change by Infineon at any time without notice.